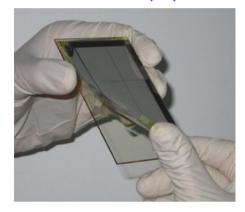
APPLICATION TO SURFACES, NANOSTRUCTURES AND DEVICES

UV-CURABLE POLYMER-BASED MATERIALS AT LPAC

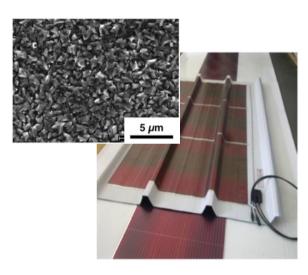
UV inks and gas-barrier films
Food & pharma packaging



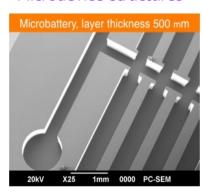
Encapsulation 'hard-coats' Flexible displays



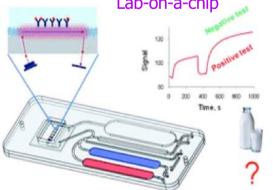
Bioinspired surfaces
Light-trapping textures
for solar cells



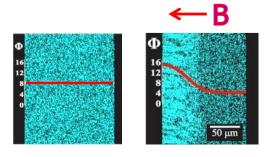
Low-stress UV resists
Microdevice structures



Optical polymer sensors
Lab-on-a-chip



Functionally graded composites
Antibacterial surfaces & ε-FGM insulators



Nanostructured devices

- Technologies
- Process methods

Application examples

optical biosensors



bioinspired surfaces



Marina Gonzalez Lazo



Lionel Wasser



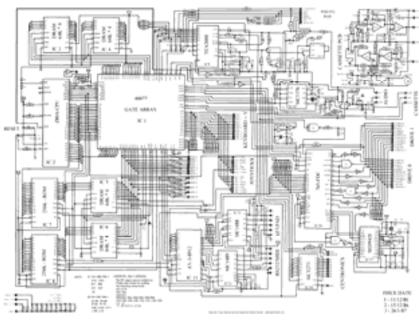
Luca Mueller

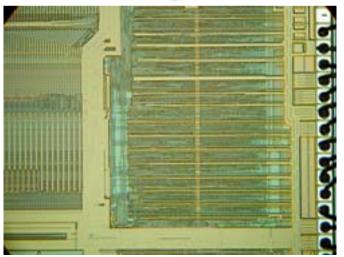


Feyza Karasu

NANOSTRUCTURED DEVICE TECHNOLOGIES







SSI: small-scale integration (early 60's)

MSI: medium-scale integration (late 60's)

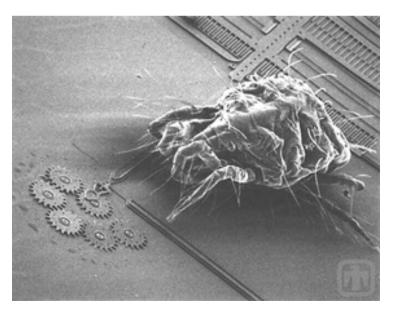
LSI: large-scale integration (mid 70's)

VLSI: very large-scale integration (80's)

ULSI (ultra large-scale integration), WSI (wafer-scale integration) SOC (system-on-chip)

NANOSTRUCTURED DEVICE TECHNOLOGIES

- Micro(Nano) Electro Mechanical System
- Micromachine / Micro System Technology (MST)
- Electrical comp.+Mechanical comp. based on CMOS process
- Application: G-MEMS (inertia MEMS) accelometer, gyro, etc.
 Optical MEMS communication, display, etc.
 Bio MEMS DNA chip, lab-on-a-chip, etc.

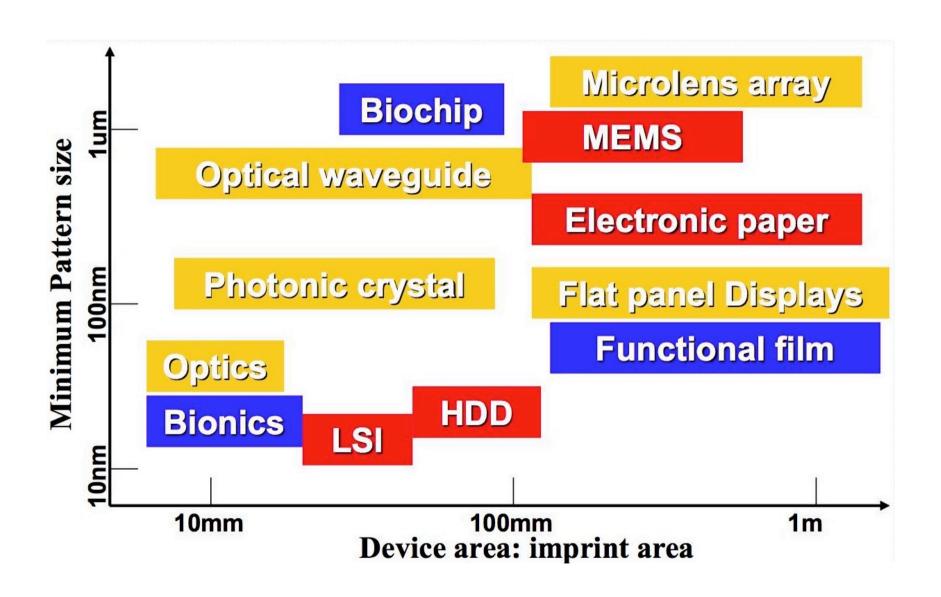






Pictures from Sandia National Laboratory http://mems.sandia.gov/gallery/images.html

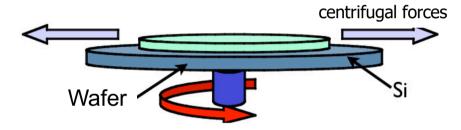
NANOSTRUCTURED DEVICE TECHNOLOGIES



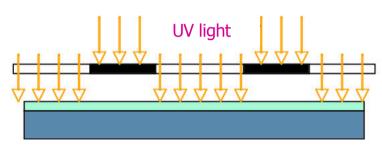
PHOTOLITHOGRAPHY

Photoresist = monomer + photoinitiator + solvent

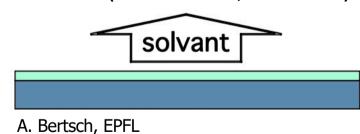
1. Spin coating (500-8'000 rpm)



3. Exposure (seconds)



2. Soft bake (90-120° C, minutes)



4. Development

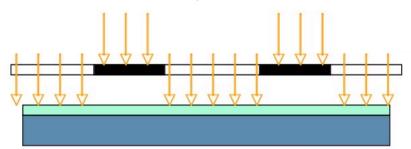


POSITIVE VS NEGATIVE RESISTS

Positive photoresist:

UV-induced chain scission Exposed parts become soluble





Development

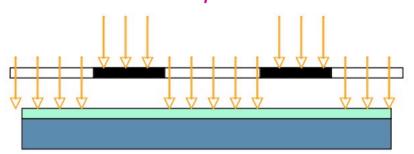


A. Bertsch, EPFL

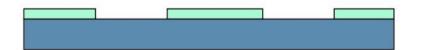
Negative photoresist:

UV-induced chain polymerization Non-exposed parts become soluble

UV exposure



Development



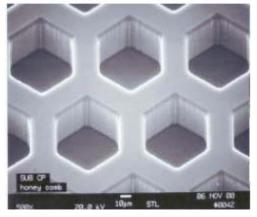
POSITIVE VS NEGATIVE RESISTS

Characteristic	Positive	Negative
Adhesion to Silicon	Fair	Excellent
Relative Cost	More Expensive	Less Expensive
Developer Base	Aqueous	Organic
Minimum Feature	0.5 µm and below	± 2 μm
Step Coverage	Better	Lower
Wet Chemical Resistance	Fair	Excellent
Resin type	Novolac	Epoxy (SU-8)

Madou, Fundamentals of Microfabrication (2002)

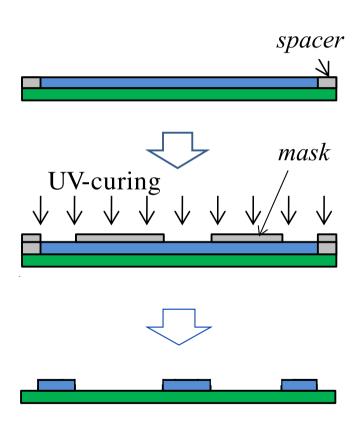
PHOTOLITHOGRAPHY: SU-8

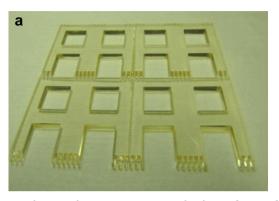
- epoxy-based negative tone photoresist
- Commercially available from Microchem and Gersteltec.
- for thick polymer microstructures with high aspect ratio
- Process flow
 substrate pretreatment ⇒ coating ⇒ soft bake ⇒ expose
 ⇒ post expose bake ⇒ development ⇒ rinse & dry
 ⇒ hard bake (optional)
- Process time: > 30 min. up to several hours.
- High resolution, high aspect ratio (+)
- High internal stress, cracks (-)



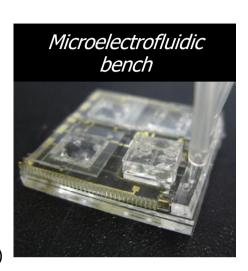
DIRECT PATTERNING

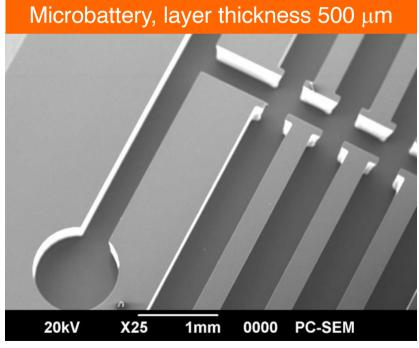
Polymer deposition





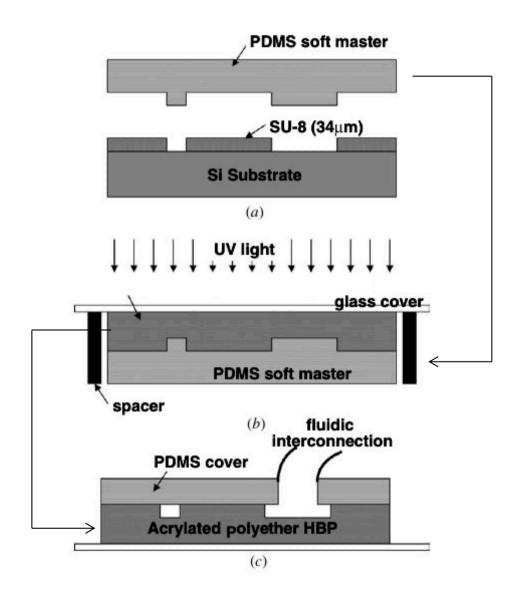


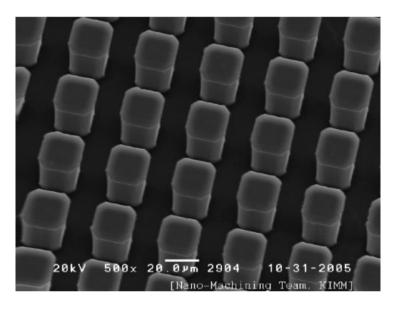


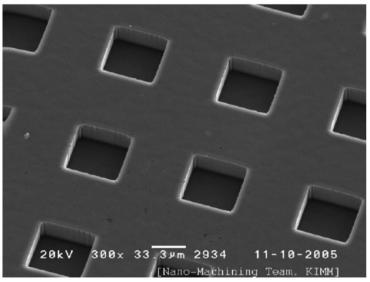


Schmidt, L.-E., J Micromech Microeng 2008

UV-MICROMOLDING





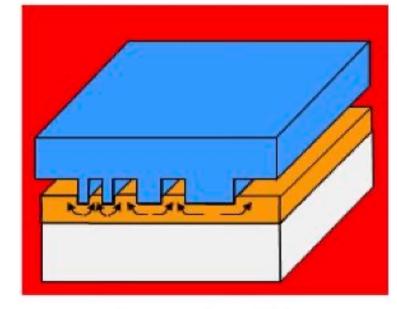


NANO-IMPRINT LITHOGRAPHY (NIL)

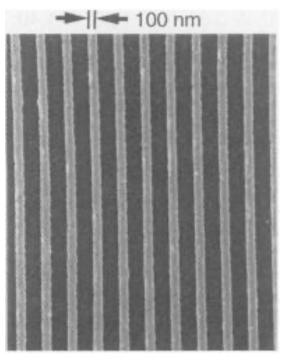
Thermal nanoimprint lithography (NIL, T-NIL)

also called

Hot embossing lithography (HEL)



Process: Compression of thin thermoplastic film between hard stamp and substrate and molding by squeeze flow

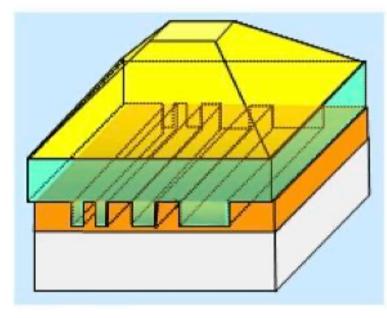


Chou et al., Science (1996)

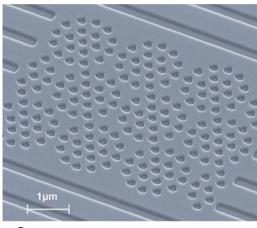
NANO-IMPRINT LITHOGRAPHY (NIL)

UVnanoimprint lithography (UV-NIL)

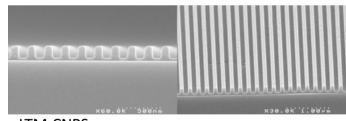
- (a) Hard stamp lithography
- (b) Soft (stamp) lithography (SL)



Process: Low pressure filling of liquid resin at room temperature by capillary action and hardening by UV-exposure through the stamp; coating by dispensing or spin coating of precursor



Suss.com



LTM-CNRS

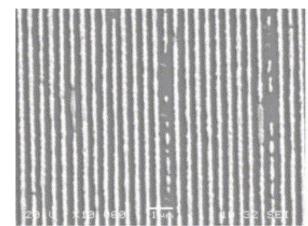
DEMOLDING AND CLOGGING!

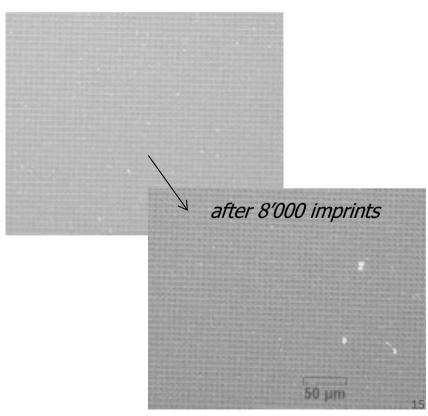
Problems:

- adhesion at the surface
- friction due to surface roughness
- shrinkage stress
- trapping of the polymer in concave geometry

Solutions:

- mold surface treatment (e.g. fluorinated silanes)
- mold design (clearance angle)
- sacrificial layers (SiO₂ ...)
- mold (solvent) cleaning
- mold filling simulation (viscoelasticity and stress effects)





Nanostructured devices

- Technologies
- Process methods

Application examples

optical biosensors



bioinspired surfaces



Marina Gonzalez Lazo



Lionel Wasser

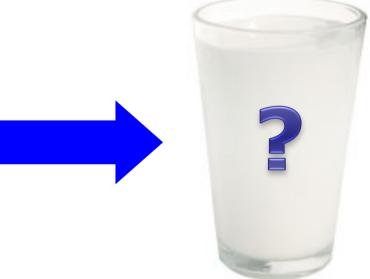


Luca Mueller



Feyza Karasu





MOTIVATION – FOOD SAFETY



Conventional techniques

- high-screening ©
- quantitative analysis ©
- semi-automatic 😐
- skilled user 🕾
- lab. environment ⊗
- expensive 🕾



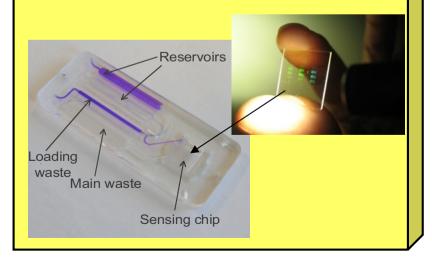
Strip tests

- cheap ©
- fast ©
- field environment ©
- quite easy to use ⊕
- max 2 antibiotic families 😊



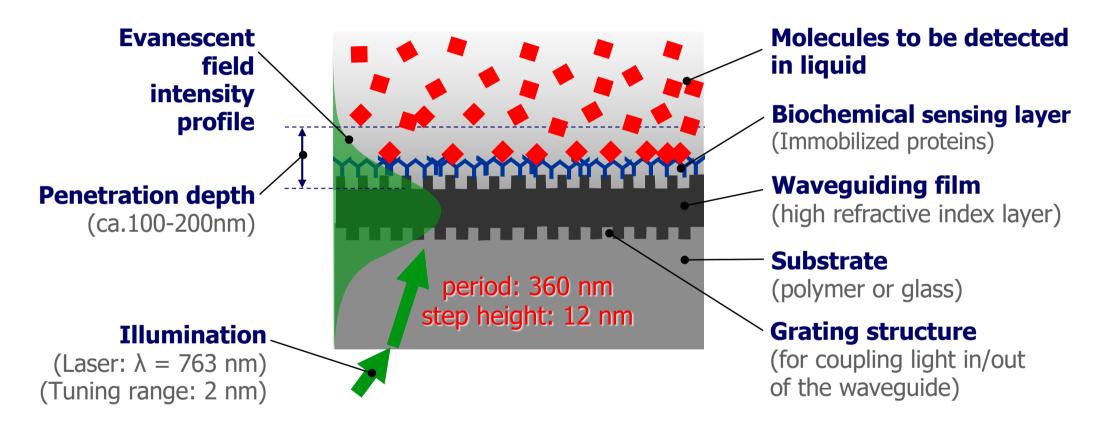
Lab-on-a-chip

- semi-quantitative
- easy to use ©
- cheap ©
- fast 😇
- fully-automated ©
- field environment



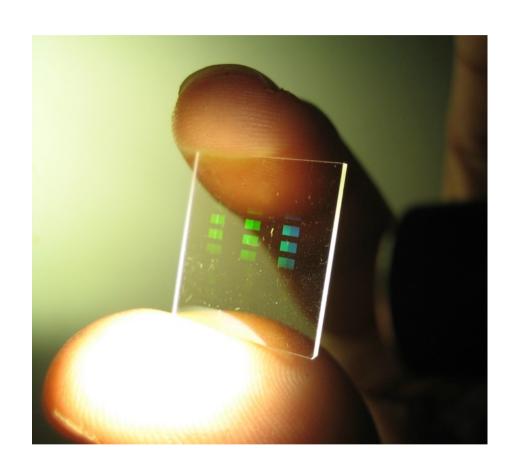
WAVELENGTH INTERROGATED OPTICAL SENSOR

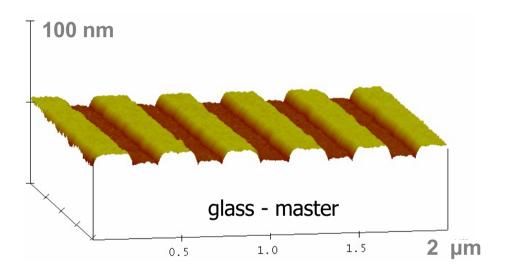
Evanescence field is highly sensitive to changes in refractive index. Device sensitivity: pg/mm²



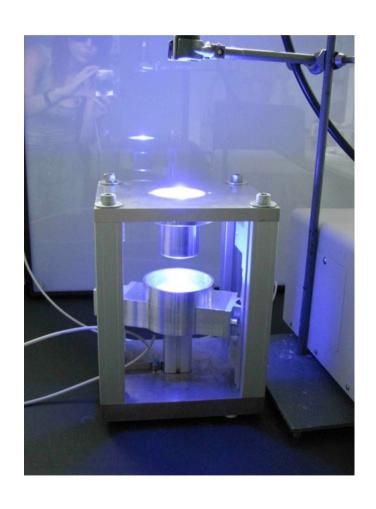


WAVELENGTH INTERROGATED OPTICAL SENSOR

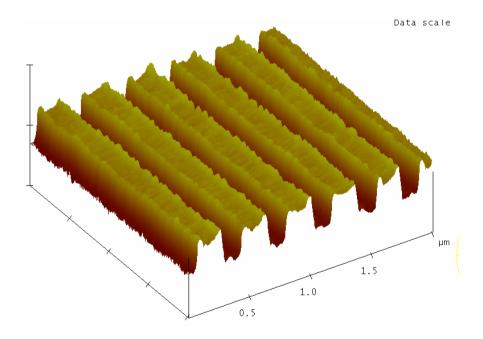




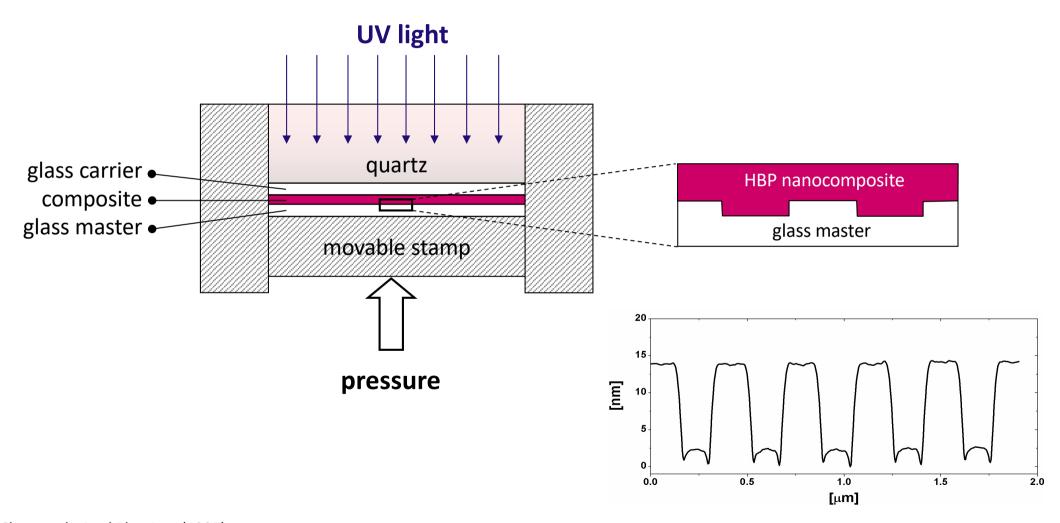
UV-NANOIMPRINT LITHOGRAPHY (UVNIL)



Polymer nanogratings for optical waveguide devices

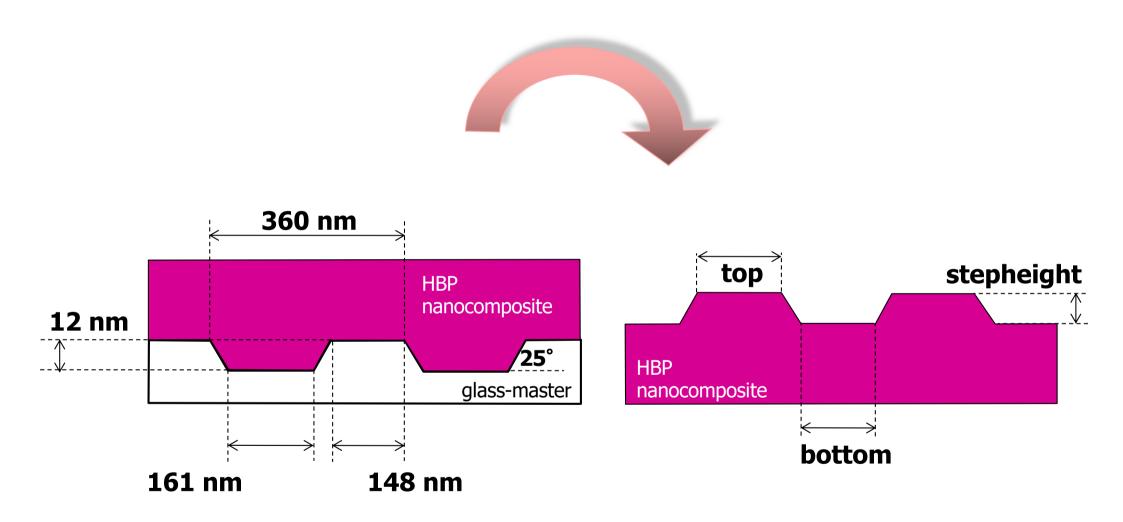


UVNIL SET-UP

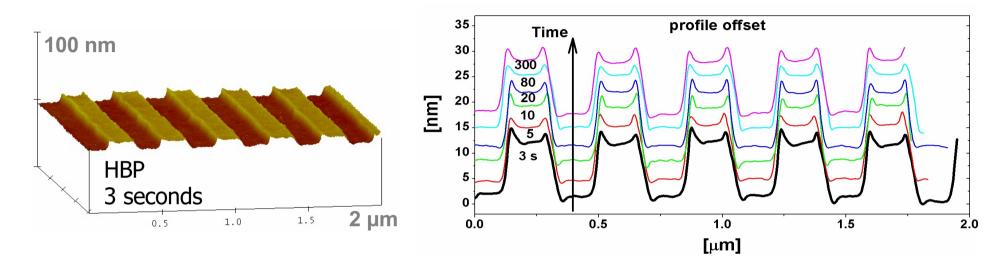


Chou et al., Appl Phys Lett (1995) Geiser et al., Macromol Sympos (2010)

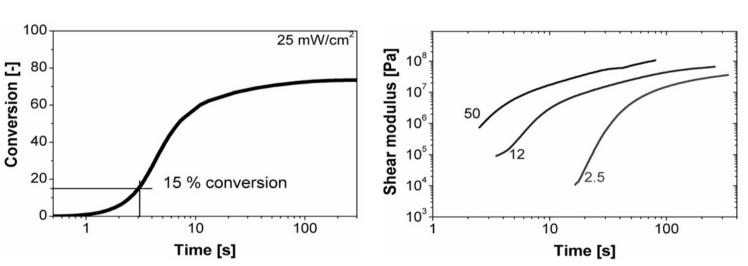
GRATING DIMENSIONS



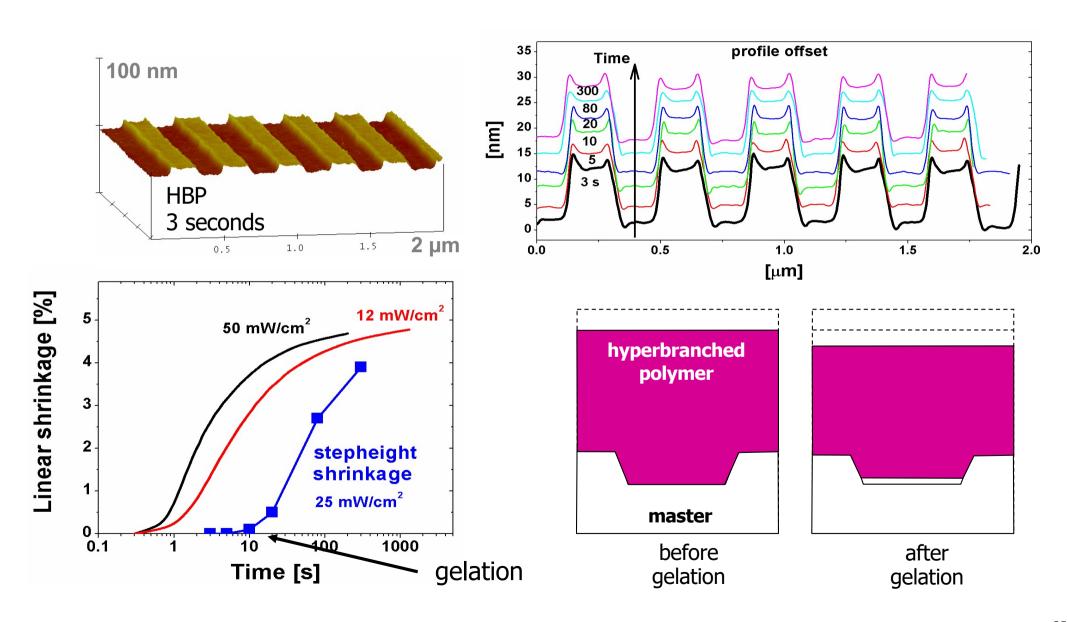
INFLUENCE OF ILLUMINATION TIME



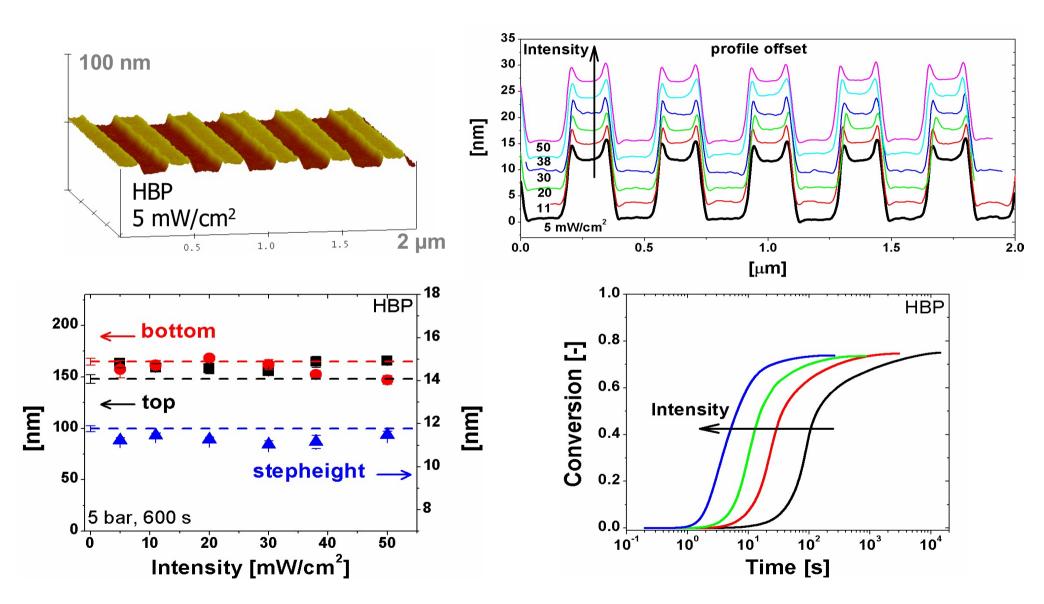
after 3 seconds: 15 % conversion 1 MPa shear modulus



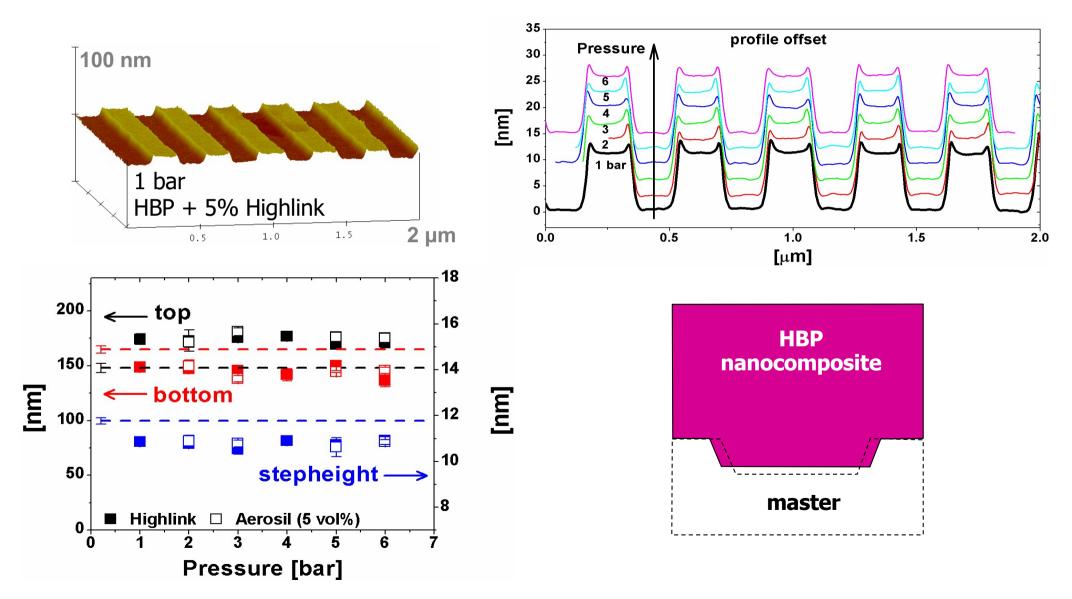
INFLUENCE OF ILLUMINATION TIME



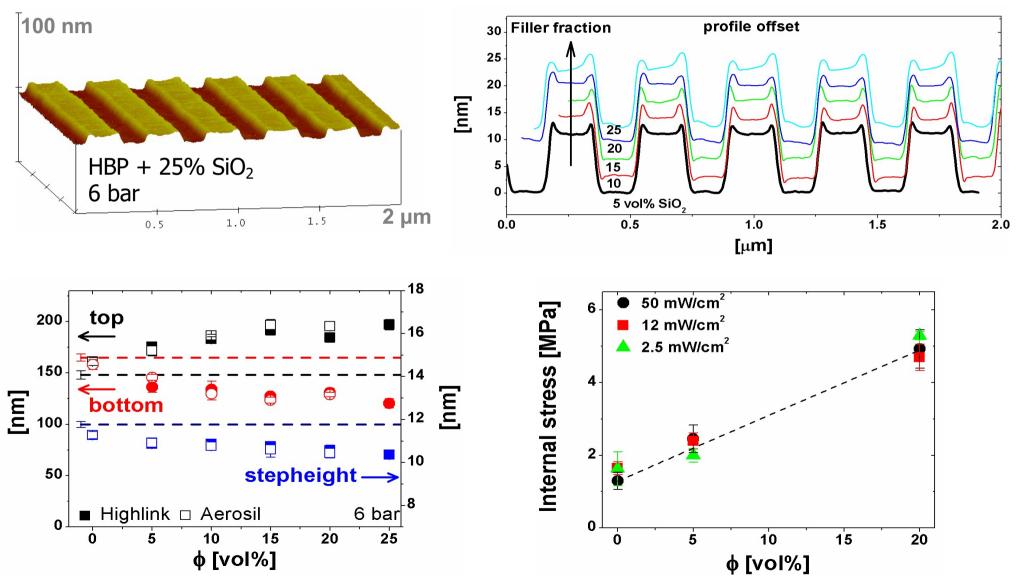
INFLUENCE OF UV-LIGHT INTENSITY



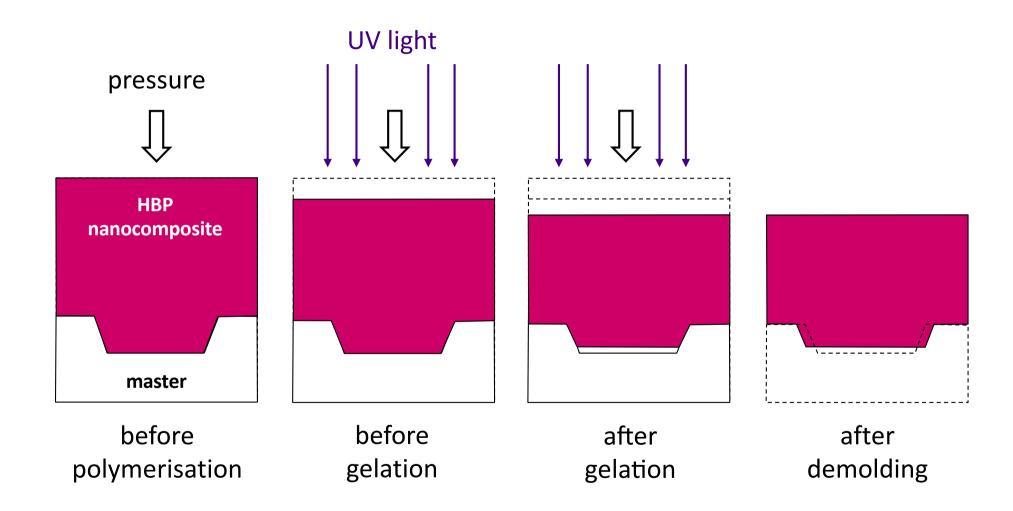
INFLUENCE OF PRESSURE



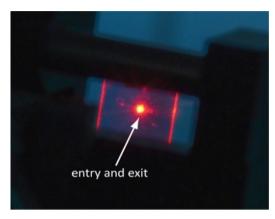
INFLUENCE OF NANOPARTICLES

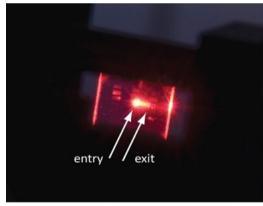


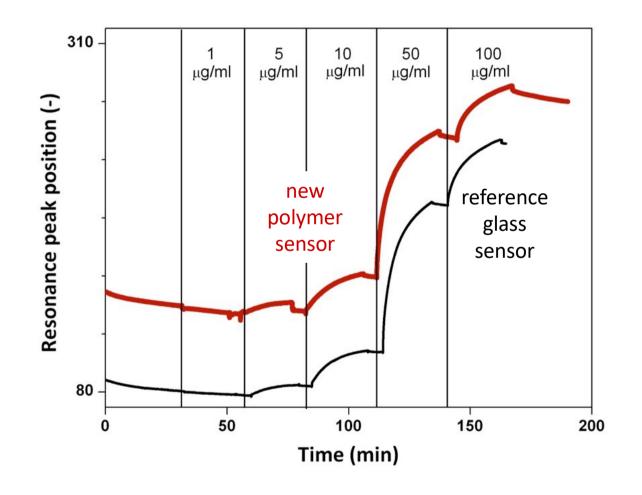
UVNIL SUMMARY



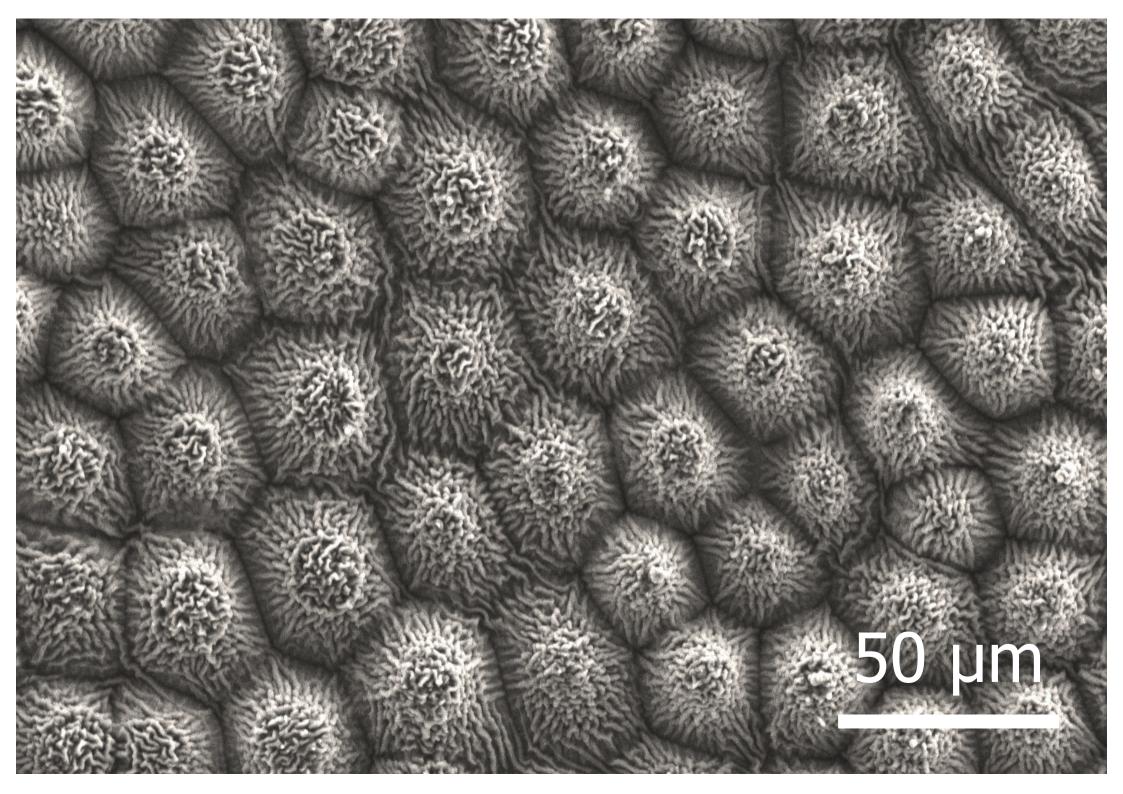
WAVELENGTH-INTERROGATED OPTICAL SENSOR WIOS

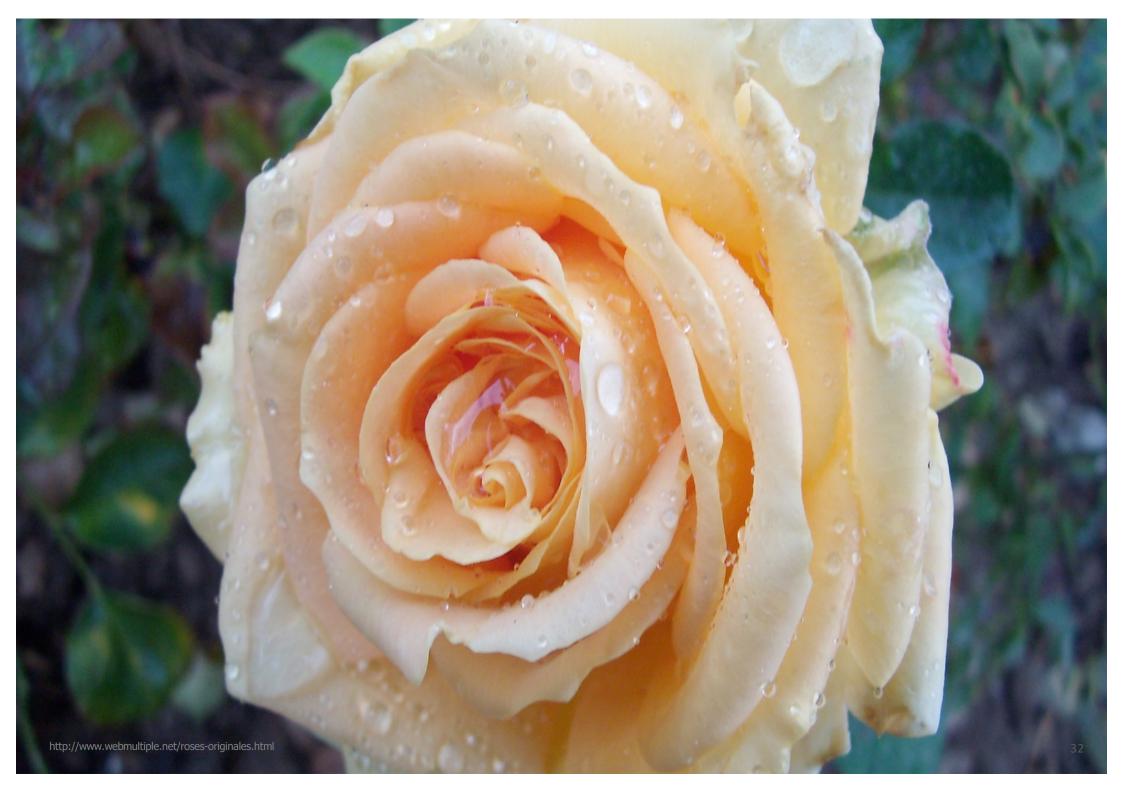


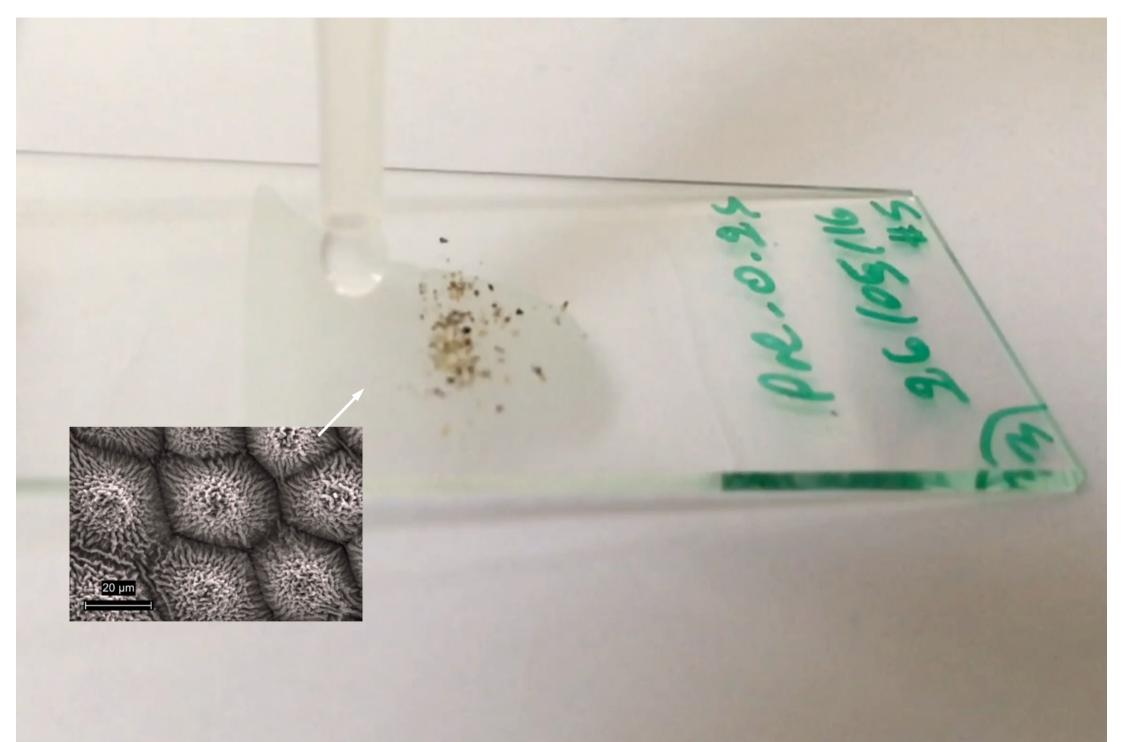




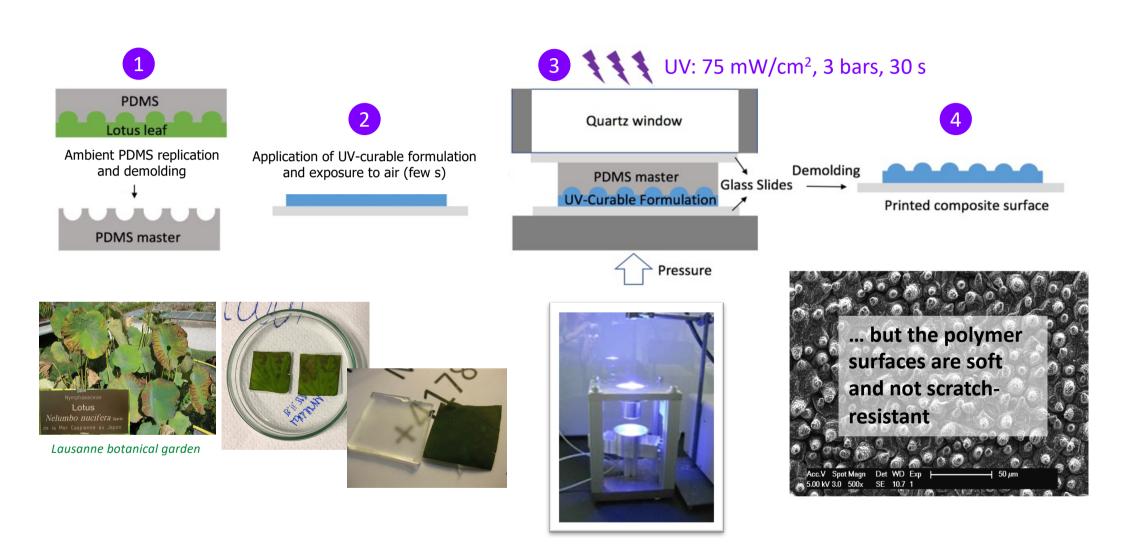
Suarez et al., Lab-on-a-chip (2009) Geiser et al, Macromol Sympos (2010)





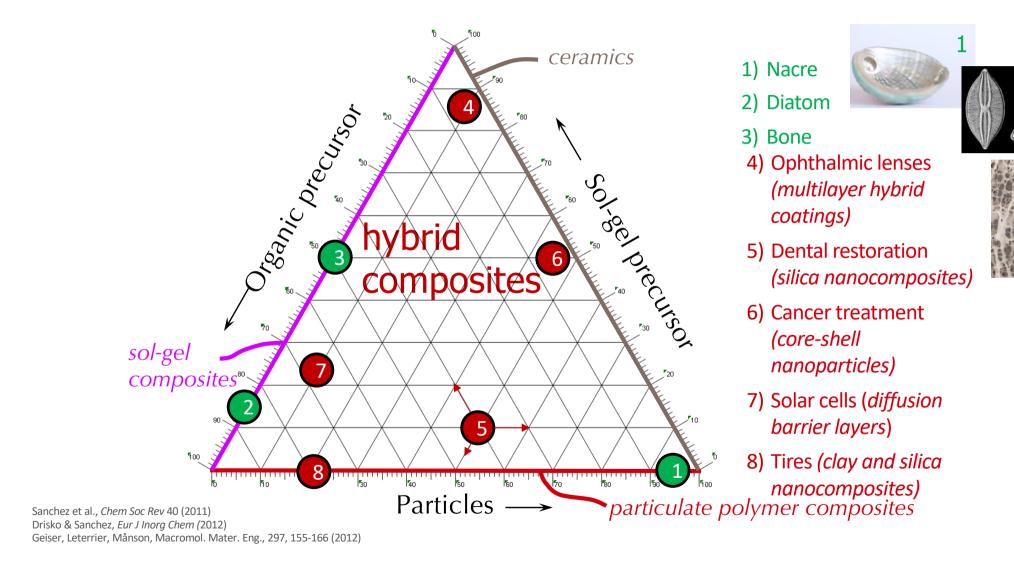


UV nanoimprint lithography process steps



Wasser, Leterrier, et al., Coatings, 8, 436 (2018)

Integrative dual-cure synthesis of hybrid composites

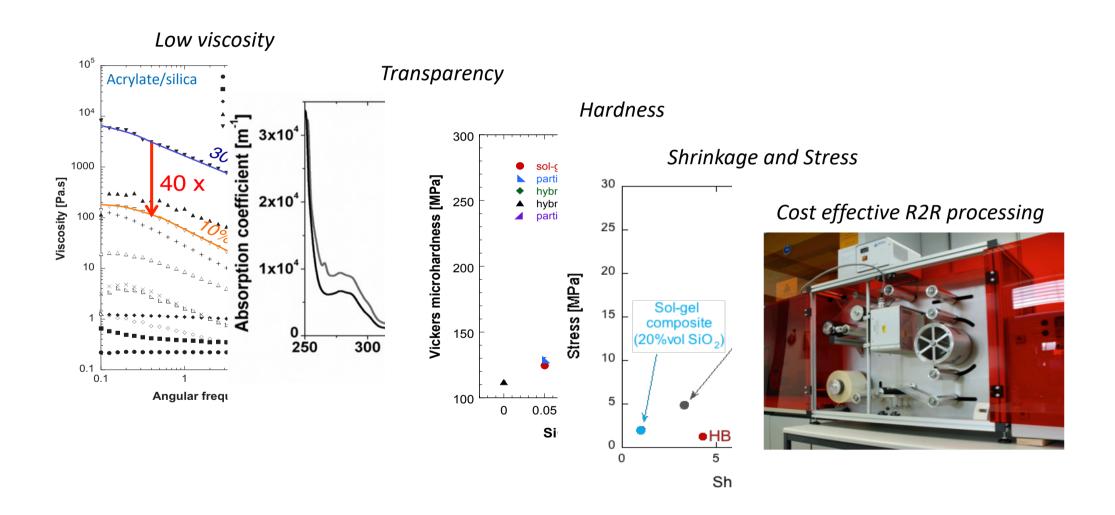


INTEGRATIVE SYNTHESIS OF HYBRID COMPOSITES

- Organic precursor: Acrylated polyester HBP (low shrinkage) Schmidt et al., J Micromech Microeng 18 (2008), Geiser et al., J Appl Polym Sci 114 (2009) Geiser et al., Macromol Sympos 296 (2010), Macromol Mater Eng 297 (2012)
- Photoinitiator: Diphenyl-(2,3,4-trimethylbenzoyl)-phosphine oxide
- SiO₂ nanoparticles: Methacrylated fused silica (12 nm, aggregates, 150 m²/g)
- Organometal precursor: tetraethylortho-silicate (TEOS)
- Coupling agent: methacryloxypropyl-trimethoxysilane (MEMO)
- - 1. Sonication of silica nanoparticles + isopropanol
 - Mixing of nanoparticles/isopropanol with HBP (1 hour at 25° C)
 - 3. Evaporation of isopropanol at 70° C
 - 4. Addition of MEMO (mixing 10 min at 25° C)
 - 5. Addition of TEOS (mixing 10 min at 25° C)
 - Addition of HCl 1M (mixing 10 min at 25° C)
 - Stirring at 25° C for 30 min
 - Dual-cure: condensation (1h; 4h) + photopolymerization (3 min before, after, or during condensation)



Why hybrid composites



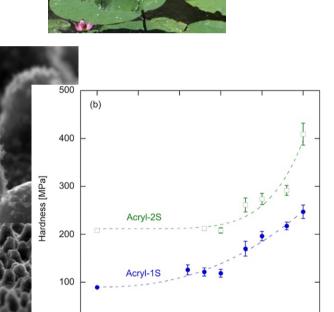
Scratch resistant and colored self-cleaning surfaces

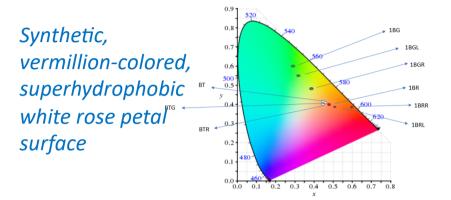
20

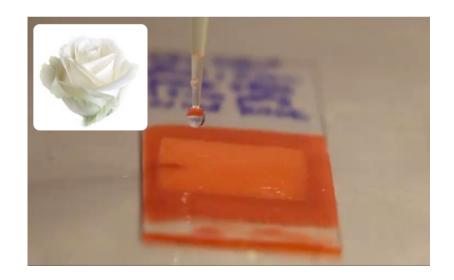
25

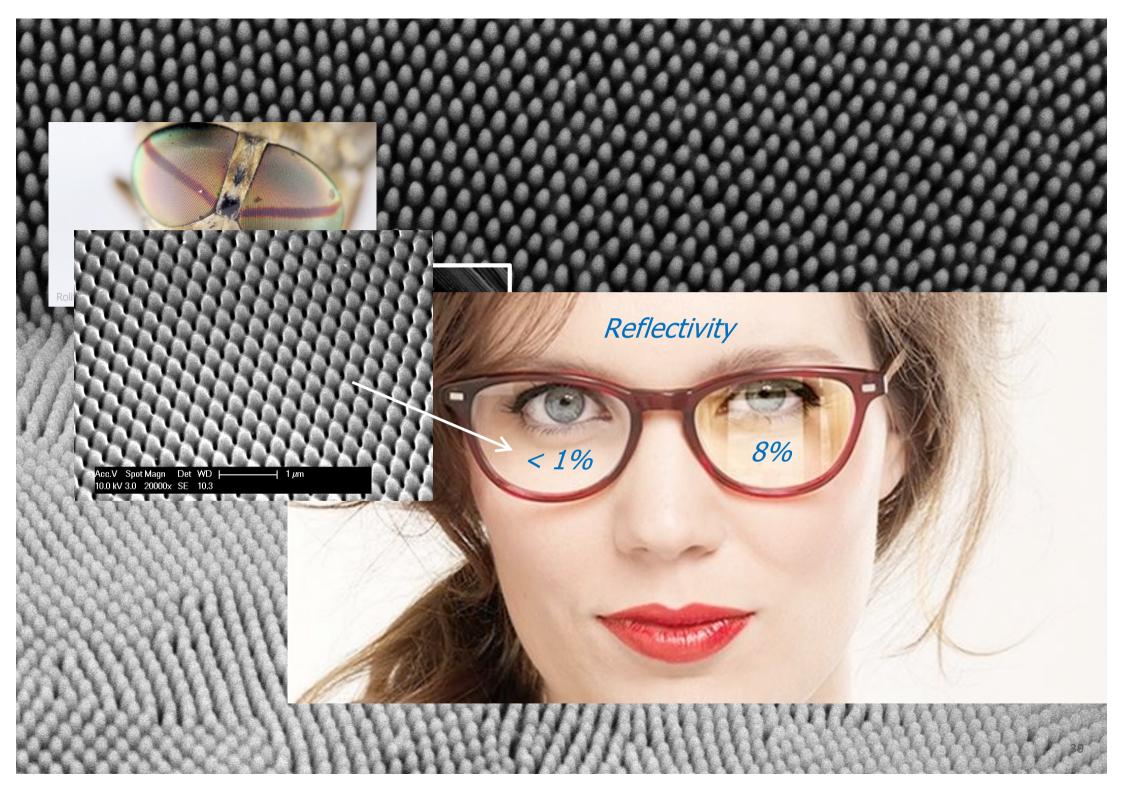
Scratch resistant: no change in WCA > 150° of hybrid composite lotus surface after 7000 sand abrasion cycles (ASTM F735–17)





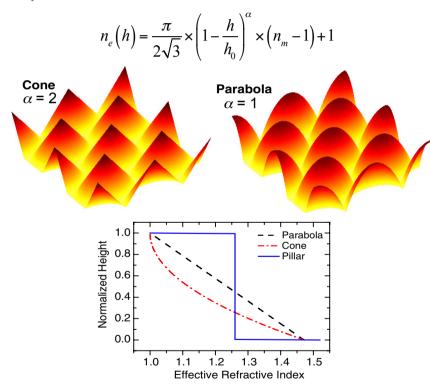


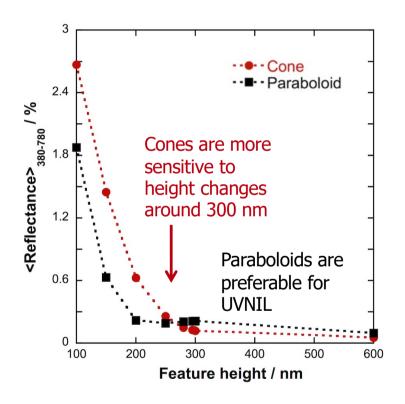




Superhard antireflective 'moth-eye' surfaces

Optical modeling of cones and paraboloid arrays: 45 layers with effective refractive index from 1 to 1.5







Summary

Photopolymerization enables numerous developments in nanostructured device technologies

- fast, simple, room temperature process
- various fabrication techniques adapted to applications / materials
- potential for 3D structures

Integrative synthesis of hybrid composites and functionally graded composites

- combination of improved process stability and thermomechanical endurance
- unique cost-performance ratio

Still, many challenges!

- optimization of filling and demolding processes
- stability of hybrid suspensions
- shape fidelity vs. process conditions
- mass production tools & materials (e.g., injection molding)

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